SCES036D - JULY 1995 - REVISED MARCH 2000

- **Member of the Texas Instruments** Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-up Performance Exceeds 250 mA Per **JESD 17**
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown**
- Packaged in Thin Very Small-Outline **Package**

NOTE: For tape and reel order entry: The DBBR package is abbreviated to GR.

description

The SN74ALVCH16282 is an 18-bit to 36-bit registered bus exchanger designed for 1.65-V to 3.6-V V_{CC} operation.

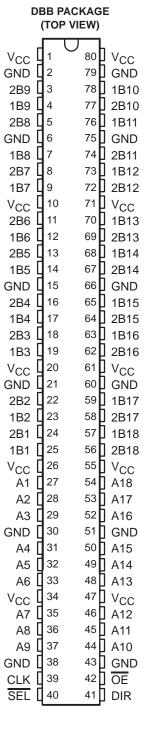
This device is intended for use in applications in which data must be transferred from a narrow high-speed bus to a wide lower-frequency bus. It is designed specifically for low-voltage (3.3-V) V_{CC} operation.

The device provides synchronous data exchange between the two ports. Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input. For data transfer in the B-to-A direction, the select (SEL) input selects 1B or 2B data for the A outputs.

For data transfer in the A-to-B direction, a two-stage pipeline is provided in the 1B path, with a single storage register in the 2B path. Data flow is controlled by the active-low output enable (\overline{OE}) and the DIR input. The DIR control pin is registered to synchronize the bus direction changes with the clock.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16282 is characterized for operation from -40°C to 85°C.





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Function Tables

A-TO-B STORAGE ($\overline{OE} = L$, DIR = H)

	INPUTS	OUTPUTS			
SEL	CLK	Α	1B	2B	
Н	X	Х	1B ₀ †	2B ₀ †	
L	\uparrow	L	L‡	X	
L	\uparrow	Н	н‡	Х	

[†]Output level before indicated steady-state input conditions were established

B-TO-A STORAGE ($\overline{OE} = L$, DIR = L)

	INPUTS						
CLK	SEL	1B	2B	Α			
1	Н	Χ	L	L§			
↑	Н	Χ	Н	Н§			
↑	L	L	X	L			
↑	L	Н	X	Н			

[§] Two CLK edges are needed to propagate the data. The data is loaded in the first register when SEL is low and propagates to the second register when SEL is high.

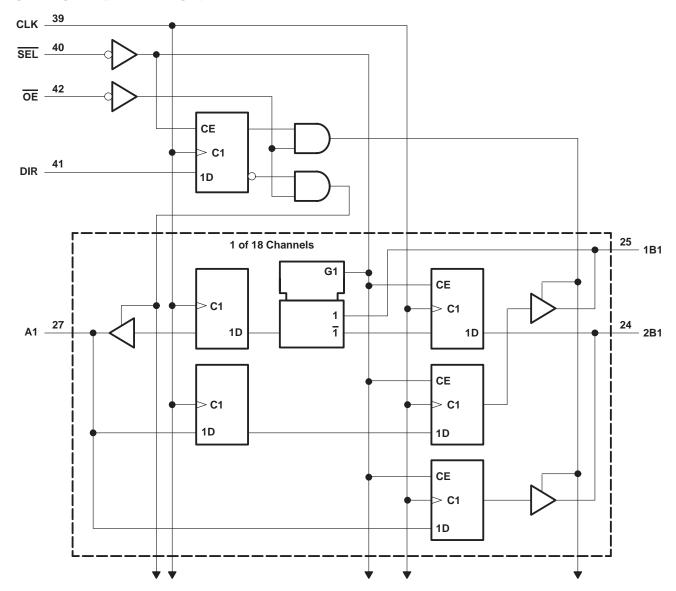
OUTPUT ENABLE

	INPUTS	OUTPUTS			
CLK	OE	DIR	Α	1B, 2B	
1	Н	Х	Z	Z	
1	L	Н	Z	Active	
↑	L	L	Active	Z	



[‡] Two CLK edges are needed to propagate

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I : Except I/O ports (see Note 1)	
I/O ports (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3)	64°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
Vcc	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
٧ıH	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
	/IH High-level input voltage /IL Low-level input voltage /I Input voltage /O Output voltage OH High-level output current OL Low-level output current	V _{CC} = 2.7 V to 3.6 V	2		
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
\vee_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
٧ _I	Input voltage		0	Vcc	V
٧o	Output voltage		0	Vcc	V
		V _{CC} = 1.65 V		-4	
1	Lligh layed autaut augreent	V _{CC} = 2.3 V		-12	mA
IOH	nign-iever output current	V _{CC} = 2.7 V		-12	mA
	Low-level input voltage Input voltage Output voltage High-level output current Low-level output current	V _{CC} = 3 V		-24	
		V _{CC} = 1.65 V		4	
1	Lavida da autorita arresant	V _{CC} = 2.3 V		12	А
IOL	Low-level output current	V _{CC} = 2.7 V	V _{CC} = 2.7 V		mA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate	•		10	ns/V
T _A	Operating free-air temperature		-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	MIN	TYPT MAX	UNIT
	I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} -0.2		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		1
	$I_{OH} = -6 \text{ mA}$	2.3 V	2		1
Voн		2.3 V	1.7		V
	$I_{OH} = -12 \text{ mA}$	2.7 V	2.2		
		3 V	2.4]
	$I_{OH} = -24 \text{ mA}$	3 V	2		
	I _{OL} = 100 μA	1.65 V to 3.6 V		0.2	
	I _{OL} = 4 mA	1.65 V		0.45	
VoL	I _{OL} = 6 mA	2.3 V		0.4] _v
	la. 12 mA	2.3 V		0.7	V
	I _{OL} = 12 mA	2.7 V		0.4	
	I _{OL} = 24 mA	3 V		0.55	
lį	$V_I = V_{CC}$ or GND	3.6 V		±5	μΑ
	V _I = 0.58 V	1.65 V	25		
	V _I = 1.07 V	1.65 V	-25		
	V _I = 0.7 V	2.3 V	45		
I _I (hold)	V _I = 1.7 V	2.3 V	-45		μΑ
	V _I = 0.8 V	3 V	75		
	V _I = 2 V	3 V	-75		
	V _I = 0 to 3.6 V [‡]	3.6 V		±500	1
loz§	$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ
ΔICC	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		750	μΑ
C _i Control inputs	$V_I = V_{CC}$ or GND	3.3 V		4	pF
Cio A or B ports	$V_O = V_{CC}$ or GND	3.3 V		8.5	pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 $[\]mbox{\ensuremath{\,\$}}$ For I/O ports, the parameter IOZ includes the input leakage current.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

			VCC =	1.8 V	V _{CC} =		VCC =	2.7 V	V _{CC} =		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			†		150		150		150	MHz
t _W	Pulse duration, CLK high or low		†		3.3		3.3		3.3		ns
		A data before CLK↑	†		2.4		2.3		2		ns
١.	Catus time	B data before CLK↑	†		2.2		2.2		1.8		
t _{su}	Setup time	DIR before CLK↑	†		2.2		2.1		1.7		
		SEL before CLK↑	†		2		2		1.8		
		A data after CLK↑	†		0.5		0.5		0.7		
1.	I laid time	B data after CLK↑	†		0.5		0.5		0.6		ns
th	Hold time	DIR after CLK↑	†		0.5		0.5		0.5		
		SEL after CLK↑	†		0.7		0.7		0.8		

[†] This information was not available at the time of publication.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INFOT)	(001F01)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		150		150		150		MHz
A . CLK	CLK	А		†	1	6.1		5.5	1.4	5	ns
^t pd	CLK	В		†	1.2	6.3		5.7	1.6	5.3	
+	ŌĒ	А		†	1.3	6.9		6.3	1.2	5.7	ns
t _{en} OE	OE	В		†	2.3	8.7		8.1	2.3	7.4	115
4	ŌĒ	А		†	1.5	7		5.6	1.8	5.7	no
^t dis	OE .	В		†	2.1	7.9		6.4	2.3	6.4	ns

[†] This information was not available at the time of publication.

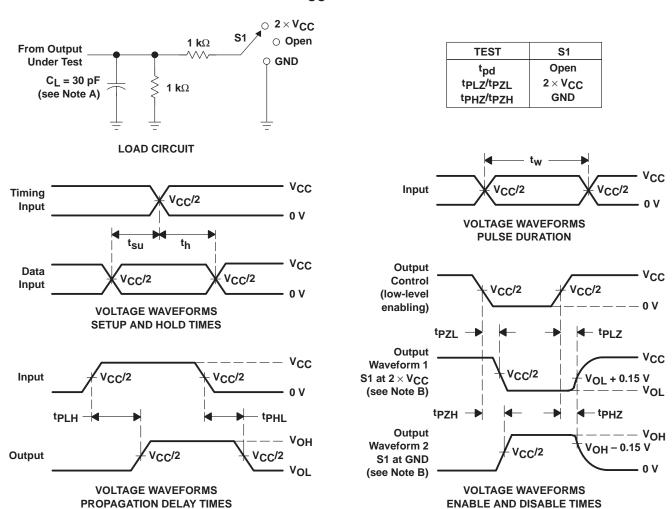
operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT	
	TANAMETEN		TEST CONDITIONS	TYP	TYP	TYP	UNIT
<u> </u>	Dower dissination conscitance	Outputs enabled	Cı = 0. f = 10 MHz	†	282	310	pF
Cpd	Power dissipation capacitance	Outputs disabled	$C_L = 0$, $f = 10 \text{ MHz}$	†	208	228	PΓ

[†] This information was not available at the time of publication.



PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.8 V

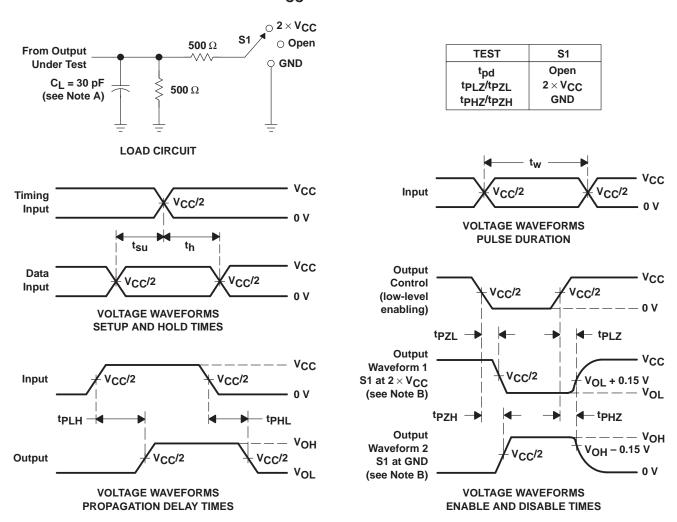


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



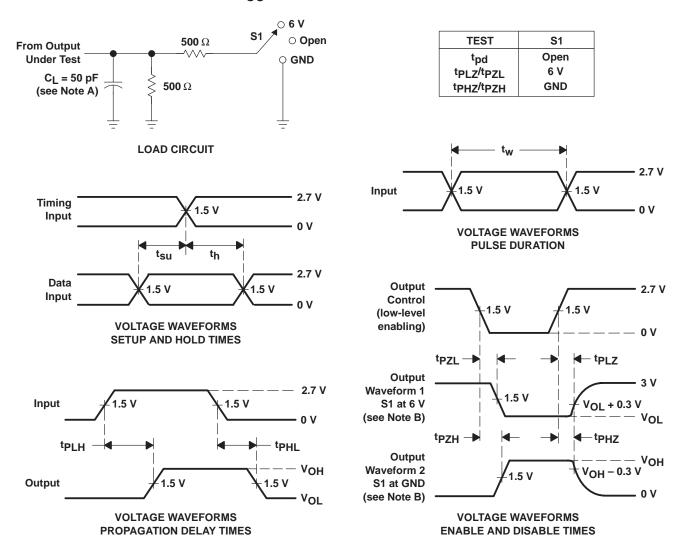
NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

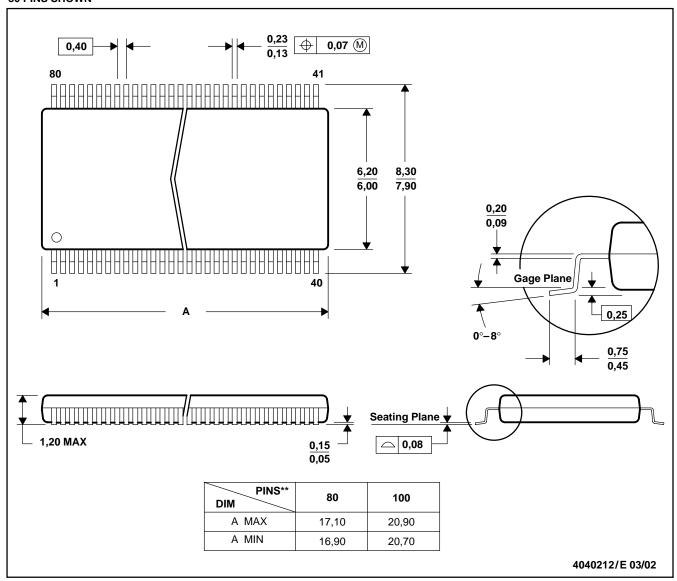
Figure 3. Load Circuit and Voltage Waveforms



DBB (R-PDSO-G**)

80 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC: 80 Pin - MO-153 Variation FF

100 Pin - MO-194 Variation BB

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Mailing Address:

Texas Instruments
Post Office Box 655303
Dallas, Texas 75265

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